

REVISIONS			
REV.	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	MAR 23/16	J. SI

FS1 - Z38 - X0Z6 - 60

CONTACT PLATING OPTION

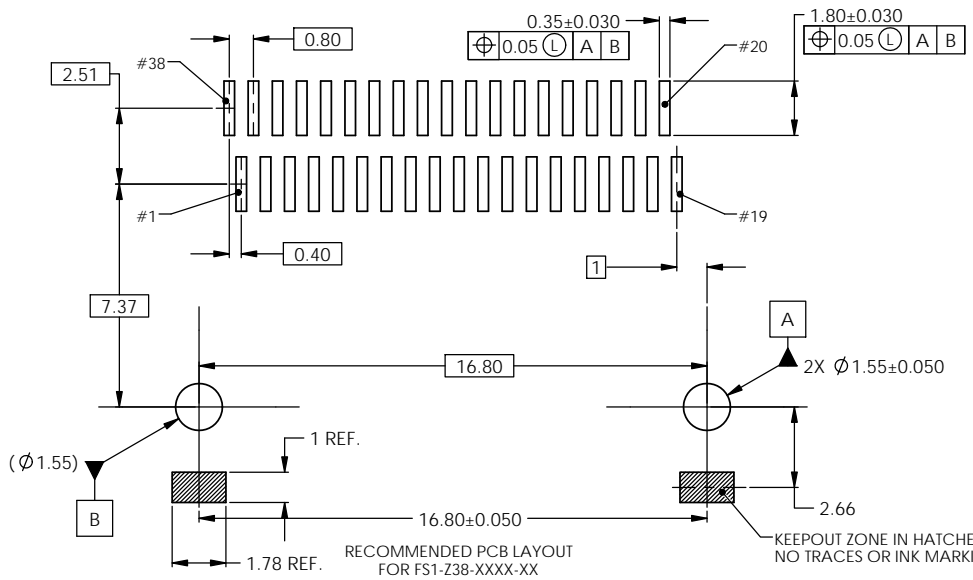
- 2** = 30 MICRO INCHES MINIMUM OF GOLD ON MATING END WITH 100 MICRO INCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50 MIN. MICRO INCHES OF NICKEL UNDER PLATE ALL OVER
- 3** = 15 MICRO INCHES MINIMUM OF GOLD ON MATING END WITH 100 MICRO INCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50 MIN. MICRO INCHES OF NICKEL UNDER PLATE ALL OVER

NOTES:

- 1) MATERIAL:
HOUSING: SOLDER REFLOW PROCESS COMPATIBLE LCP, UL94V-0
CONTACTS: PHOSPHOR BRONZE
RESONANCE DAMPENING FEATURE: CONDUCTIVE POLYMER
- 2) ROHS COMPLIANT



DO NOT SCALE DRAWING



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UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:		APPROVALS	DATE	Amphenol High Speed Interconnects	
DECIMALS	ANGLES	DRAWN	MAR23/16	A Division of Amphenol Corp. www.amphenol-highspeed.com	
.X ± 0.2	± 2°	DESIGNED	MAR23/16	UltraPort OSFP 4x28	
XX ± 0.1		CHECKED	MAR23/16	38 POSITION CONNECTOR	
MATERIAL AND FINISH		DRAWN	MAR23/16		
ENG. REL. NO.		CAL. APP'D	MAR23/16		
CODE IDENT. NO.		ENG. APP'D	MAR23/16	SCALE	PROJECT
03554		J. SI	MAR23/16	NTS	FS1